

NIHON SUPERIOR CO. LTD.



LEAD-FREE HOT AIR LEVELLING

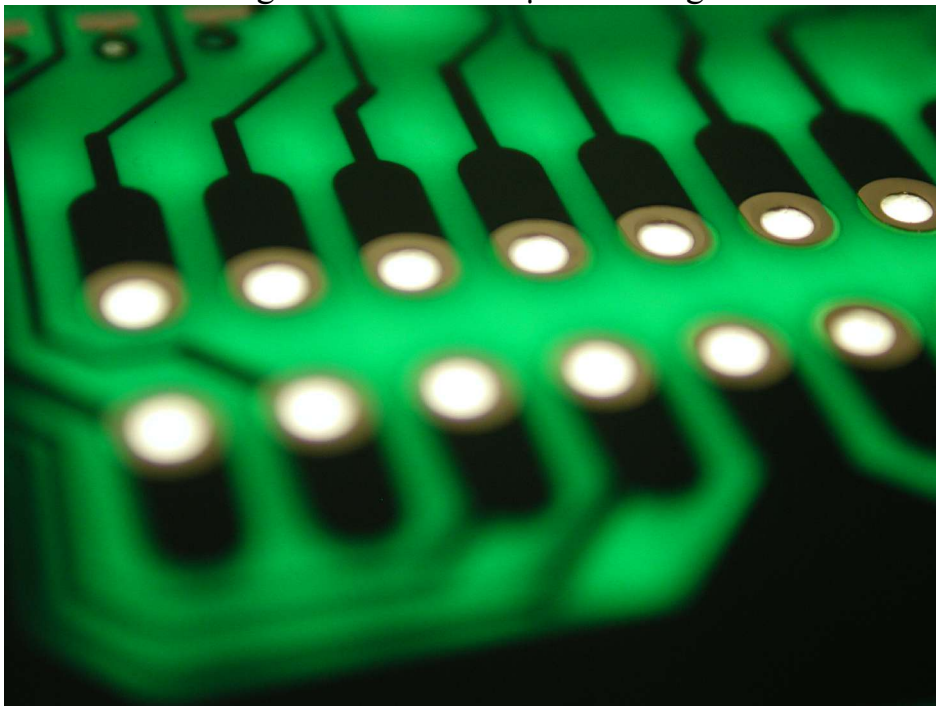
CLEAR THROUGH-HOLES AND SMOOTH BRIGHT PADS ON HOT AIR LEVELLED BOARDS AT A 265°C SOLDER POT TEMPERATURE ARE POSSIBLE WITH NIHON SUPERIOR'S SN100CL

- Smooth coverage of pads and hole walls
- Uniform coating on pads and hole walls, even on the shoulder
- Bridge-free coating of 0.8mm pitch pads

COMMERCIAL PRODUCTION EXPERIENCE HAS CONFIRMED THAT BOARDS HOT AIR LEVELLED WITH SN100CL CAN PROVIDE THE LONG SHELF LIFE LEAD-FREE BOARD FINISH THAT THE ELECTRONICS INDUSTRY HAS BEEN LOOKING FOR.

The patented Ni addition to the Sn-Cu eutectic ensures :

- Good wetting of the board surface at 265°C
- Good hole clearance
- Smooth bright finish on pads and hole walls
- Uniform coating thickness of 3-5µm for long extended solderability



DKL Metals Limited

Avontoun Works, Linlithgow, West Lothian, EH49 6QD, U.K.

Telephone: +44(0) 1506 847710
E-mail: sales@dklmetals.co.uk

Fax: +44 (0)1506 848199
Web: www.dklmetals.co.uk